

Custom High Performance Cooling Solutions w/ maxiGRIP™ Attachment



ATS Part#: **ATS-59007-C1-R0**
 Description: maxiGRIP™ HS Assembly, T766, BLACK-ANODIZED, 35MM COMP

Heat Sink Type: **maxiFLOW**
 Heat Sink Attachment: **maxiGRIP**
 Equivalent Part Number: **ATS-59007-C2-R0 Discontinued**

**Image above is for illustration purpose only.*


Features & Benefits

- **maxiFLOW™** design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- **maxiGRIP™** attachment applies steady, even pressure to the component and does not require holes in the PCB
- Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- Comes pre-assembled with high performance, phase changing, thermal interface material
- Designed for flip-chip processors such as Freescale MPCs
- "Keep-Out" Requirements: An "Un-Populated" border zone of 5mm around the component is necessary to facilitate the Installation/Removal of the **maxiGRIP™**. Please refer to the **maxiGRIP™** Keep-Out Guidelines and **maxiGRIP™** Installation/Removal Instructions for further details.

Thermal Performance

| AIR VELOCITY | | @200 LFM 1.0 M/S | @300 LFM 1.5 M/S | @400 LFM 2.0 M/S | @500 LFM 2.5 M/S | @600 LFM 3.0 M/S | @700 LFM 3.5 M/S | @800 LFM 4.0 M/S |
|--------------------|---------------|---------------------|---------------------|---------------------|---------------------|---------------------|---------------------|---------------------|
| THERMAL RESISTANCE | Unducted Flow | 2.42 °C/W | 1.98 °C/W | 1.70 °C/W | 1.53 °C/W | 1.40 °C/W | 1.30 °C/W | 1.20 °C/W |
| | Ducted Flow | 1.60 | n/a | n/a | n/a | n/a | n/a | n/a |

Product Detail

| Schematic Image | Dimension A | Dimension B | Dimension C | Dimension D | TIM | Finish |
|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------|-------------|-------------|-------------|------|----------------|
|  <p><i>*Image above is for illustration purpose only.</i></p> | 35.0 mm | 46.0 mm | 16.0 mm | 68.6 mm | T766 | BLACK-ANODIZED |
| <p>Notes:</p> <ul style="list-style-type: none"> • Dimension B refers to component size • Dimension C is the heat sink height from the bottom of the base to the top of the fin field. • ATS-59007-C2-R0 is the exact heat sink assembly with an equivalent thermal interface material (Saint Gobain C1100F). NOTE: Saint Gobain C1100F is discontinued effective 12/31/10. • Thermal performance data are provided for reference only. Actual performance may vary by application. • ATS reserves the right to update or change its products without notice to improve the design or performance. • ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant. • Contact ATS to learn about custom options available. | | | | | | |

For more information, to find a distributor or to place an order, please contact us at 781-769-2800 (North America), sales@qats.com or www.qats.com.

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